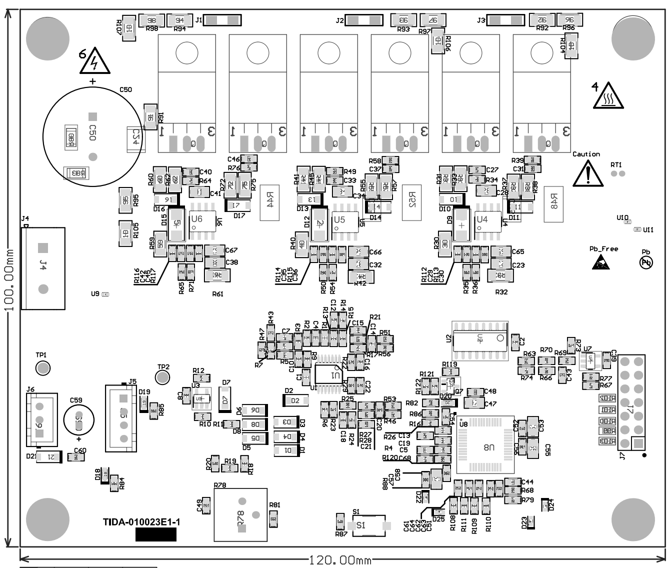
Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0.40mil	3.5	
3	Top Layer	Copper	1.40mil		
4	Dielectric1	FR-4	59.20mil	4.8	
5	Bottom Layer	Copper	1.40mil		
6	Bottom Solder	Solder Resist	0.40mil	3.5	
7	Bottom Overlay				

DESIGN INFORMATION

MIN. TRACK WIDTH: 8 MIL
MIN. CLEARANCE: 0.2 mm
MIN. VIA PAD SIZE: 24 MIL
MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL PER IPC-D-275 CLASS 2 LEVEL C
REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL
HOLE SIZE TOLERANCE (UNLESS OTHERWISE SPECIFIED): +/- 3 MIL

MATERIAL: [ ] FR-408 [X] FR-4 High Tg [ ] OTHER
THICKNESS: [X] 62 MIL (1.6mm) +/-10% [ ] OTHER
TOLERANCE: [X] ANSI IPC-6012 TYPE 3 CLASS 2 [ ] OTHER +/-
BOW & TWIST: [X] ANSI IPC-6012 TYPE 3 CLASS 2 [ ] OTHER +/-
DRILLING:
REFERENCE: [X] AS SHOWN [X] NC_DRILL FILES
PTH COPPER THICKNESS: [X] 20-30 um [ ] OTHER
BOARD FINISH:
SILKSCREEN: [X] TOP [X] BOTTOM
SILKSCREEN COLOR: [X] WHITE [ ] OTHER
SOLDER RESIST COLOR: [X] GREEN [ ] OTHER
[X] MATTE [ ] SEMI-GLOSS
SURFACE FINISH: [X] IMMERSION GOLD (ENIG) [ ] ENEPIG [ ] IMM. TIN/SILVER OR EQUIV [ ] OTHER
ARRAY/PANEL: [ ] CUT AND TRIM PER M1 BOARD OUTLINE [ ] N.C. ROUTE [X] V. SCORE
CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBS TO MEET OR EXCEED THE REQUIREMENTS OF:
[X] ANSI IPC-A-600F CLASS -> [ ] 1 [X] 2 [ ] 3
[X] RoHS [ ] OTHER PER ORDER
ALL BOARDS MUST MEET OR EXCEED UL94-V0 REQUIREMENTS.
PCB MUST BEAR THE UL94V-0 UL REGISTERED MATERIAL ID NUMBER
ADDITIONAL REQUIREMENTS:
MICROSECTION: [ ] YES
BARE BOARD ELEC. TEST: [ ] NONE [X] REQUIRED [ ] PER ORDER
[ ] XX MIL VIAS REQUIRE NON-CONDUCTIVE FILL AND PLANARIZE
[ ] XX MIL VIAS REQUIRE CONDUCTIVE FILL AND PLANARIZE
[ ] OUTER XX MIL VIAS REQUIRE 50 OHM SINGLE-ENDED IMPEDANCE
[ ] LAYER 2 & 3 (INNER LAYERS) XX MIL WIDE, XX MIL SPACE TRACES REQUIRE 100 OHM DIFFERENTIAL IMPEDANCE



ZZ1 Install label in silkscreened box after final wash. Text shall be 8 pt font. Text shall be per the Label Table in the PDF schematic.

ZZ1 H11 H12

TEXAS INSTRUMENTS

FID4 FID5 FID6 H13 H14

1000.00mil

COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED
ASSEMBLY VARIANT: [No Variations]

PCB ARTWORK VIEWED FROM TOP SIDE | BOARD #: XXXXXXX | REV: E1 | SVN REV: Not in version control
LAYER NAME = Top Overlay | TID #: N/A
PLOT NAME = Top Layer Assembly Drawing | GENERATED : 10/30/2018 9:17:25 AM | TEXAS INSTRUMENTS

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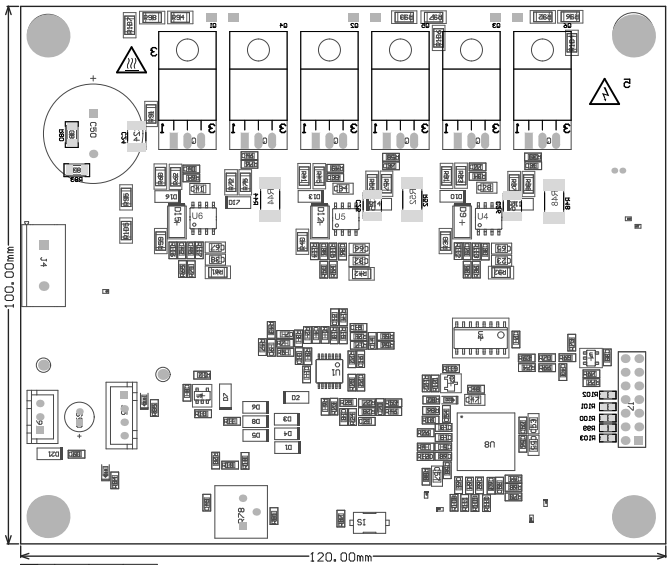
TEXAS INSTRUMENTS

PROJECT TITLE: Change in menu Project|Project Options|Parameters
DESIGNED FOR: Public Release
FILE NAME: TIDA-010023_PCB.PCBDOC
ENGINEER: Enter name of project
LAYOUT BY: Who did the Layout?
SCALE: 1.00
ALTIUM DESIGNER VERSION: 17.1.9.592

String

Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0.40mil	3.5	
3	Top Layer	Copper	1.40mil		
4	DielectricI	FR-4	59.20mil	4.8	
5	Bottom Layer	Copper	1.40mil		
6	Bottom Solder	Solder Resist	0.40mil	3.5	
7	Bottom Overlay				



Z21 Install label in silkscreened box after final wash. Text shall be 8 pt font. Text shall be per the Label Table in the PDF schematic.

COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED

ASSEMBLY VARIANT: [No Variations]

1000.00mil

DESIGN INFORMATION	
MIN. TRACK WIDTH:	8 MIL
MIN. CLEARANCE:	0.2 mm
MIN. VIA PAD SIZE:	24 MIL
MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL PER IPC-D-275 CLASS 2 LEVEL C	
REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL	
HOLE SIZE TOLERANCE (UNLESS OTHERWISE SPECIFIED): +/- 3 MIL	
MATERIAL:	[ ] FR-408 [X] FR-4 High Tg [ ] OTHER
THICKNESS:	[X] 62 MIL (1.6mm) +/-10% [ ] OTHER
TOLERANCE:	[X] ANSI IPC-6012 TYPE 3 CLASS 2 [ ] OTHER +/-
BOW & TWIST:	[X] ANSI IPC-6012 TYPE 3 CLASS 2 [ ] OTHER +/-
DRILLING:	
REFERENCE:	[X] AS SHOWN [X] NC_DRILL FILES
PTH COPPER THICKNESS:	[X] 20-30 um [ ] OTHER
BOARD FINISH:	
SILKSCREEN:	[X] TOP [X] BOTTOM
SILKSCREEN COLOR:	[X] WHITE [ ] OTHER
SOLDER RESIST COLOR:	[X] GREEN [ ] OTHER [X] MATTE [ ] SEMI-GLOSS
SURFACE FINISH:	[X] IMMERSION GOLD (ENIG) [ ] ENEPIG [ ] IMM. TIN/SILVER OR EQUIV [ ] OTHER
ARRAY/PANEL:	[ ] CUT AND TRIM PER M1 BOARD OUTLINE [ ] N.C. ROUTE [X] V. SCORE
CERTIFICATION:	MATERIALS AND WORKMANSHIP FOR ALL PCBS TO MEET OR EXCEED THE REQUIREMENTS OF: [X] ANSI IPC-A-600F CLASS -> [ ] 1 [X] 2 [ ] 3 [X] RoHS [ ] OTHER PER ORDER
ALL BOARDS MUST MEET OR EXCEED UL94-V0 REQUIREMENTS. PCB MUST BEAR THE UL94V-0 UL REGISTERED MATERIAL ID NUMBER	
ADDITIONAL REQUIREMENTS:	
MICROSECTION:	[ ] YES
BARE BOARD ELEC. TEST:	[ ] NONE [X] REQUIRED [ ] PER ORDER
[ ] XX MIL VIAS REQUIRE NON-CONDUCTIVE FILL AND PLANARIZE	
[ ] XX MIL VIAS REQUIRE CONDUCTIVE FILL AND PLANARIZE	
[ ] OUTER XX MIL VIAS REQUIRE 50 OHM SINGLE-ENDED IMPEDANCE	
[ ] LAYER 2 & 3 (INNER LAYERS) XX MIL WIDE, XX MIL SPACE TRACES REQUIRE 100 OHM DIFFERENTIAL IMPEDANCE	

TEXAS INSTRUMENTS

PROJECT TITLE: Change in menu Project|Project Options|Parameters

DESIGNED FOR: Public Release

FILE NAME: TIDA-010023_PCB.PCBDOC

ENGINEER: Enter name of project	LAYOUT BY: Who did the Layout?
SCALE: 1.00	ALTIUM DESIGNER VERSION: 17.1.9.592

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